

"OMNIFET":

FULLY AUTOPROTECTED POWER MOSFET

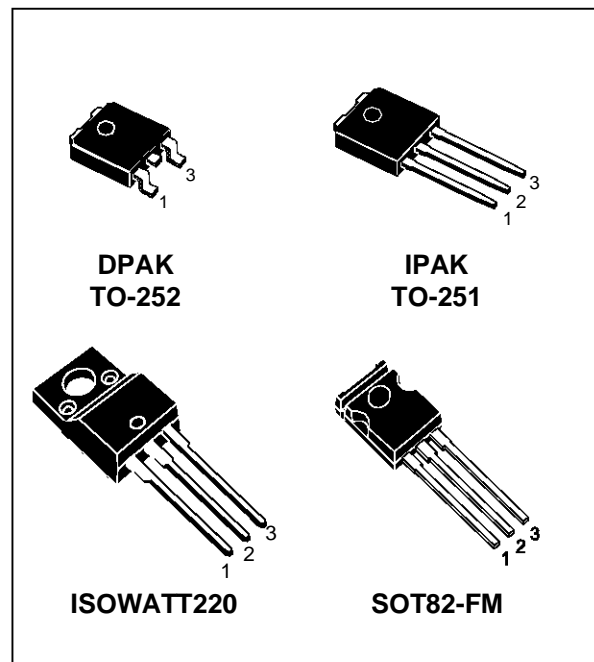
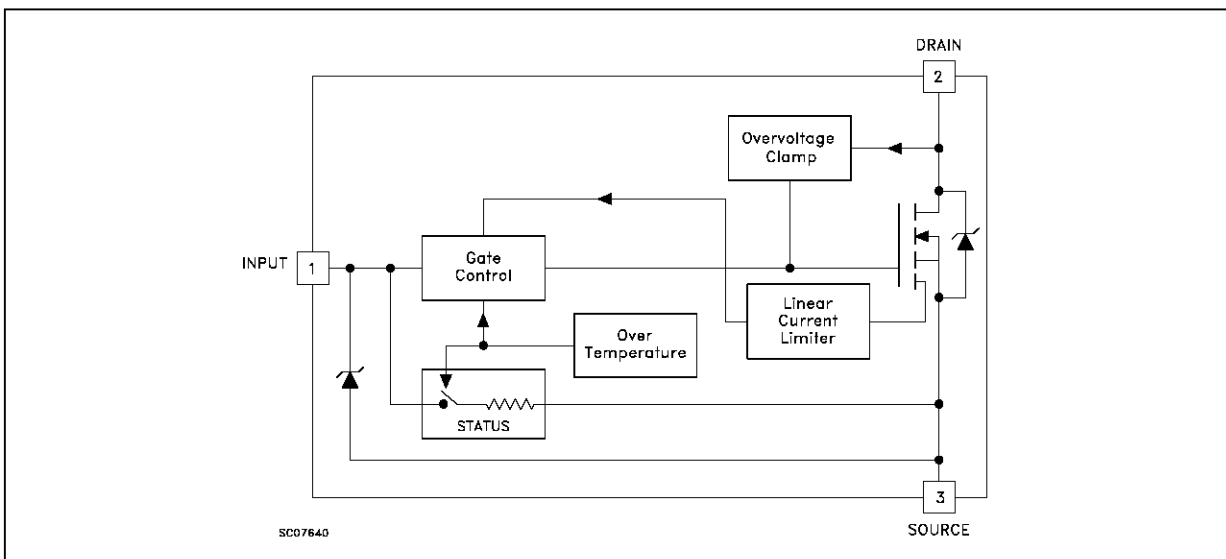
TYPE	V _{clamp}	R _{DS(on)}	I _{lim}
VND5N07	70 V	0.2 Ω	5 A
VND5N07-1	70 V	0.2 Ω	5 A
VNP5N07FI	70 V	0.2 Ω	5 A
VNK5N07FM	70 V	0.2 Ω	5 A

- LINEAR CURRENT LIMITATION
- THERMAL SHUT DOWN
- SHORT CIRCUIT PROTECTION
- INTEGRATED CLAMP
- LOW CURRENT DRAWN FROM INPUT PIN
- DIAGNOSTIC FEEDBACK THROUGH INPUT PIN
- ESD PROTECTION
- DIRECT ACCESS TO THE GATE OF THE POWER MOSFET (ANALOG DRIVING)
- COMPATIBLE WITH STANDARD POWER MOSFET

DESCRIPTION

The VND5N07, VND5N07-1, VNP5N07FI and VNK5N07FM are monolithic devices made using SGS-THOMSON Vertical Intelligent Power M0 Technology, intended for replacement of standard power MOSFETS in DC to 50 KHz applications. Built-in thermal shut-down, linear current limitation and overvoltage clamp protect

BLOCK DIAGRAM



the chip in harsh environments.

Fault feedback can be detected by monitoring the voltage at the input pin.

VND5N07/VND5N07-1/VNP5N07FI/VNK5N07FM

ABSOLUTE MAXIMUM RATING

Symbol	Parameter	Value			Unit
		DPAK IPAK	ISOWATT220	SOT-82FM	
V _{DS}	Drain-source Voltage (V _{in} = 0)	Internally Clamped			V
V _{in}	Input Voltage	18			V
I _D	Drain Current	Internally Limited			A
I _R	Reverse DC Output Current	-7			A
V _{esd}	Electrostatic Discharge (C= 100 pF, R=1.5 KΩ)	2000			V
P _{tot}	Total Dissipation at T _c = 25 °C	60	24	9	W
T _j	Operating Junction Temperature	Internally Limited			°C
T _c	Case Operating Temperature	Internally Limited			°C
T _{stg}	Storage Temperature	-55 to 150			°C

THERMAL DATA

		DPAK/IPAK	ISOWATT220	SOT82-FM	
R _{thj-case}	Thermal Resistance Junction-case Max	3.75	5.2	14	°C/W
R _{thj-amb}	Thermal Resistance Junction-ambient Max	100	62.5	100	°C/W

ELECTRICAL CHARACTERISTICS (T_{case} = 25 °C unless otherwise specified)

OFF

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
V _{CLAMP}	Drain-source Clamp Voltage	I _D = 200 mA V _{in} = 0	60	70	80	V
V _{CLTH}	Drain-source Clamp Threshold Voltage	I _D = 2 mA V _{in} = 0	55			V
V _{INCL}	Input-Source Reverse Clamp Voltage	I _{in} = -1 mA	-1		-0.3	V
I _{DSS}	Zero Input Voltage Drain Current (V _{in} = 0)	V _{DS} = 13 V V _{in} = 0 V _{DS} = 25 V V _{in} = 0			50 200	μA μA
I _{ISS}	Supply Current from Input Pin	V _{DS} = 0 V V _{in} = 10 V		250	500	μA

ON (*)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
V _{IN(th)}	Input Threshold Voltage	V _{DS} = V _{in} I _D + I _{in} = 1 mA	0.8		3	V
R _{DS(on)}	Static Drain-source On Resistance	V _{in} = 10 V I _D = 2.5 A V _{in} = 5 V I _D = 2.5 A			0.200 0.280	Ω Ω

ELECTRICAL CHARACTERISTICS (continued)

DYNAMIC

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
g_{fs} (*)	Forward Transconductance	$V_{DS} = 13\text{ V}$ $I_D = 2.5\text{ A}$	3	4		S
C_{oss}	Output Capacitance	$V_{DS} = 13\text{ V}$ $f = 1\text{ MHz}$ $V_{in} = 0$		200	300	pF

SWITCHING ()**

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
$t_{d(on)}$	Turn-on Delay Time	$V_{DD} = 15\text{ V}$ $I_d = 2.5\text{ A}$		50	100	ns
t_r	Rise Time	$V_{gen} = 10\text{ V}$ $R_{gen} = 10\ \Omega$		60	100	ns
$t_{d(off)}$	Turn-off Delay Time	(see figure 3)		150	300	ns
t_f	Fall Time			40	80	ns
$t_{d(on)}$	Turn-on Delay Time	$V_{DD} = 15\text{ V}$ $I_d = 2.5\text{ A}$		150	250	ns
t_r	Rise Time	$V_{gen} = 10\text{ V}$ $R_{gen} = 1000\ \Omega$		400	600	ns
$t_{d(off)}$	Turn-off Delay Time	(see figure 3)		3900	5000	ns
t_f	Fall Time			1100	1600	ns
$(di/dt)_{on}$	Turn-on Current Slope	$V_{DD} = 15\text{ V}$ $I_D = 2.5\text{ A}$ $V_{in} = 10\text{ V}$ $R_{gen} = 10\ \Omega$		80		A/ μ s
Q_i	Total Input Charge	$V_{DD} = 12\text{ V}$ $I_D = 2.5\text{ A}$ $V_{in} = 10\text{ V}$		18		nC

SOURCE DRAIN DIODE

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
V_{SD} (*)	Forward On Voltage	$I_{SD} = 2.5\text{ A}$ $V_{in} = 0$			1.6	V
t_{rr} (**)	Reverse Recovery Time	$I_{SD} = 2.5\text{ A}$ $di/dt = 100\text{ A}/\mu\text{s}$ $V_{DD} = 30\text{ V}$ $T_j = 25\text{ }^\circ\text{C}$		150		ns
Q_{rr} (**)	Reverse Recovery Charge	(see test circuit, figure 5)		0.3		μC
I_{RRM} (**)	Reverse Recovery Current			5.7		A

PROTECTION

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
I_{lim}	Drain Current Limit	$V_{in} = 10\text{ V}$ $V_{DS} = 13\text{ V}$ $V_{in} = 5\text{ V}$ $V_{DS} = 13\text{ V}$	3.5 3.5	5 5	7 7	A A
t_{dim} (**)	Step Response Current Limit	$V_{in} = 10\text{ V}$ $V_{in} = 5\text{ V}$		15 40	20 60	μs μs
T_{jsh} (**)	Overtemperature Shutdown		150			$^\circ\text{C}$
T_{jrs} (**)	Overtemperature Reset		135			$^\circ\text{C}$
I_{gf} (**)	Fault Sink Current	$V_{in} = 10\text{ V}$ $V_{DS} = 13\text{ V}$ $V_{in} = 5\text{ V}$ $V_{DS} = 13\text{ V}$		50 20		mA mA
E_{as} (**)	Single Pulse Avalanche Energy	starting $T_j = 25\text{ }^\circ\text{C}$ $V_{DD} = 20\text{ V}$ $V_{in} = 10\text{ V}$ $R_{gen} = 1\text{ K}\Omega$ $L = 10\text{ mH}$	0.2			J

(*) Pulsed: Pulse duration = 300 μs , duty cycle 1.5 %

(**) Parameters guaranteed by design/characterization

PROTECTION FEATURES

During normal operation, the Input pin is electrically connected to the gate of the internal power MOSFET. The device then behaves like a standard power MOSFET and can be used as a switch from DC to 50 KHz. The only difference from the user's standpoint is that a small DC current (I_{ISS}) flows into the Input pin in order to supply the internal circuitry.

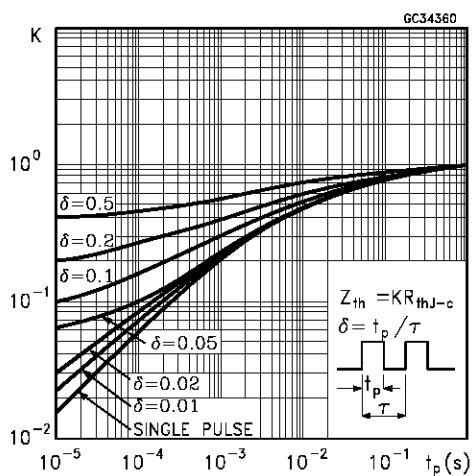
The device integrates:

- **OVERVOLTAGE CLAMP PROTECTION:** internally set at 70V, along with the rugged avalanche characteristics of the Power MOSFET stage give this device unrivalled ruggedness and energy handling capability. This feature is mainly important when driving inductive loads.
- **LINEAR CURRENT LIMITER CIRCUIT:** limits the drain current I_d to I_{lim} whatever the Input pin voltage. When the current limiter is active, the device operates in the linear region, so power dissipation may exceed the capability of the heatsink. Both case and junction temperatures increase, and if this phase lasts long enough, junction temperature may reach the overtemperature threshold T_{jsh} .

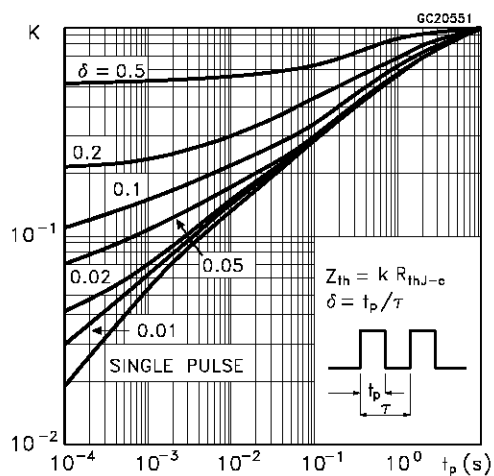
- **OVERTEMPERATURE AND SHORT CIRCUIT PROTECTION:** these are based on sensing the chip temperature and are not dependent on the input voltage. The location of the sensing element on the chip in the power stage area ensures fast, accurate detection of the junction temperature. Overtemperature cutout occurs at minimum 150°C. The device is automatically restarted when the chip temperature falls below 135°C.
- **STATUS FEEDBACK:** In the case of an overtemperature fault condition, a Status Feedback is provided through the Input pin. The internal protection circuit disconnects the input from the gate and connects it instead to ground via an equivalent resistance of 100 Ω . The failure can be detected by monitoring the voltage at the Input pin, which will be close to ground potential.

Additional features of this device are ESD protection according to the Human Body model and the ability to be driven from a TTL Logic circuit (with a small increase in $R_{DS(on)}$).

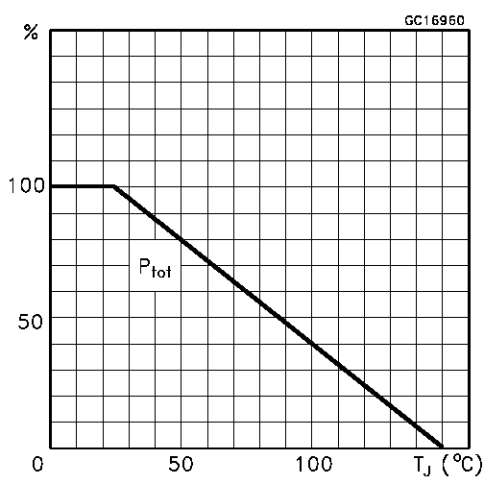
Thermal Impedance For DPAK / IPAK



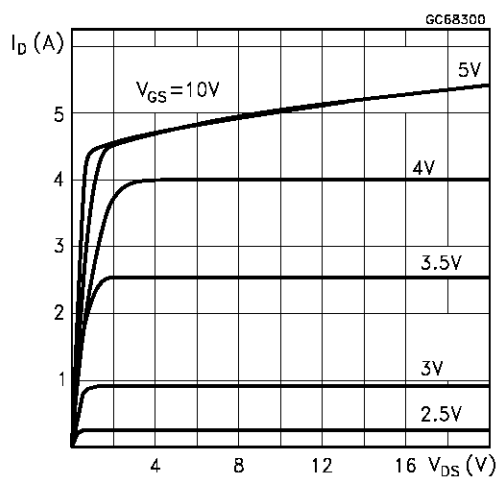
Thermal Impedance For ISOWATT220



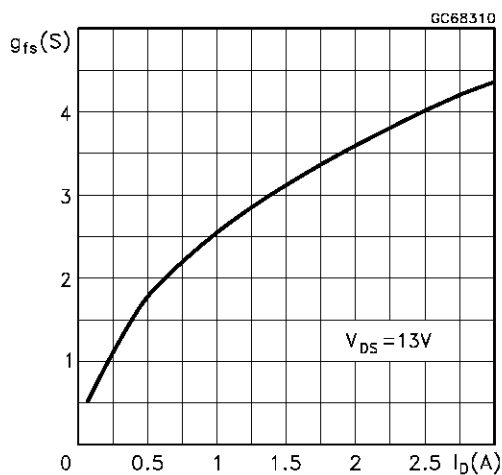
Derating Curve



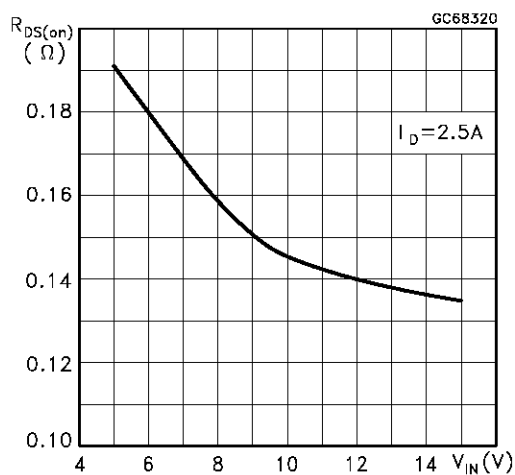
Output Characteristics



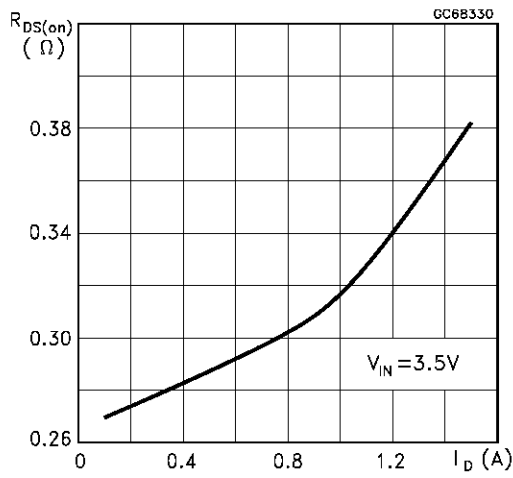
Transconductance



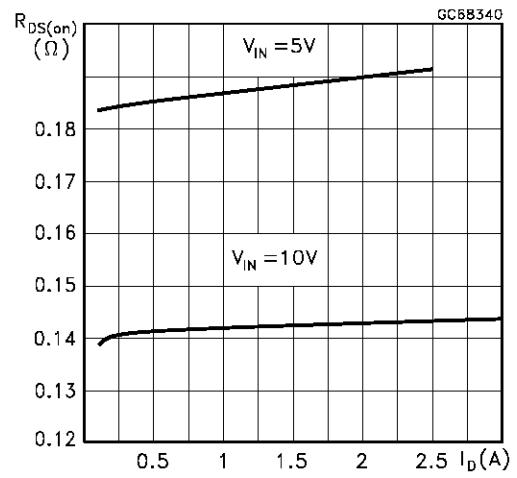
Static Drain-Source On Resistance vs Input Voltage



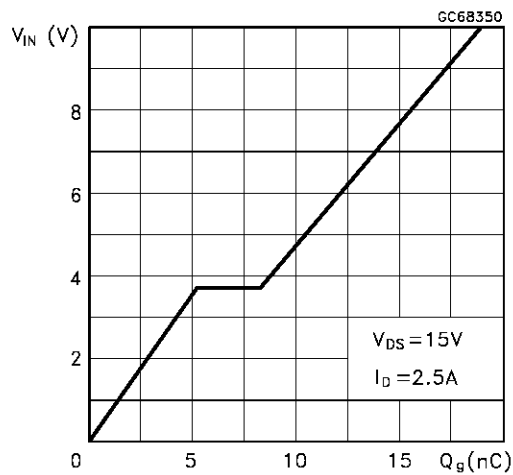
Static Drain-Source On Resistance



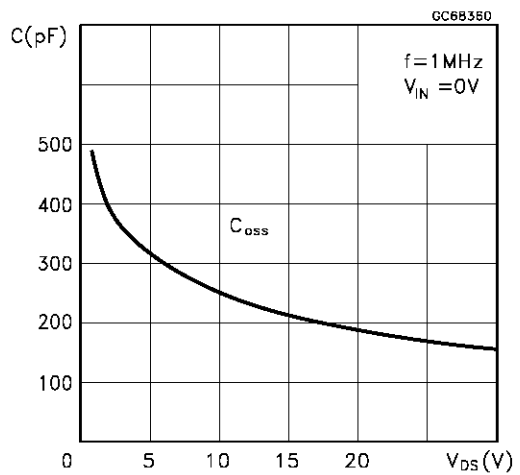
Static Drain-Source On Resistance



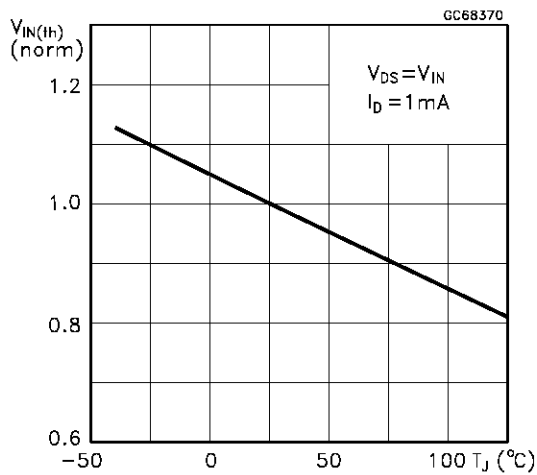
Input Charge vs Input Voltage



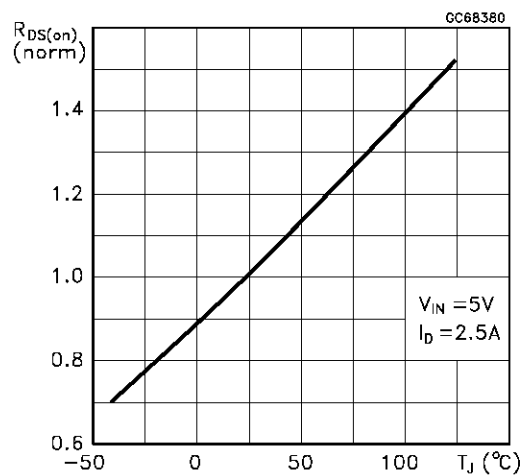
Capacitance Variations



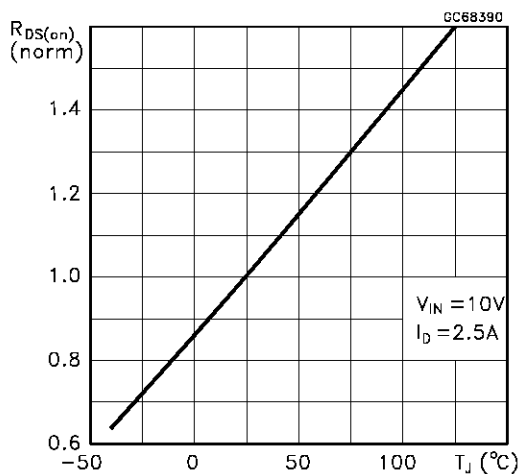
Normalized Input Threshold Voltage vs Temperature



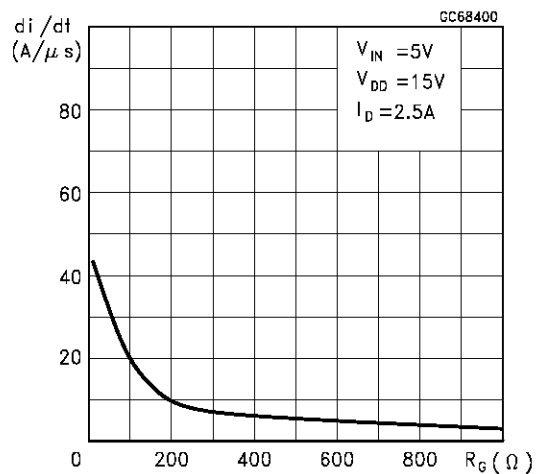
Normalized On Resistance vs Temperature



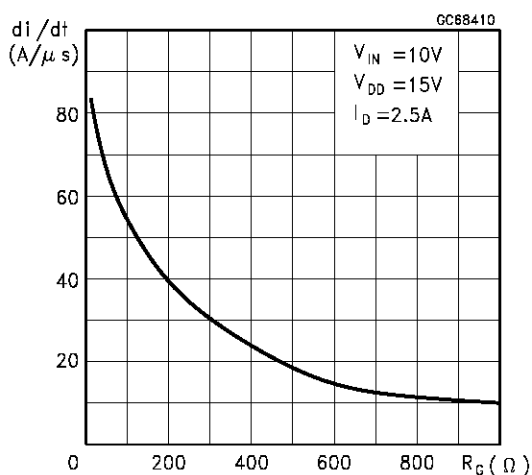
Normalized On Resistance vs Temperature



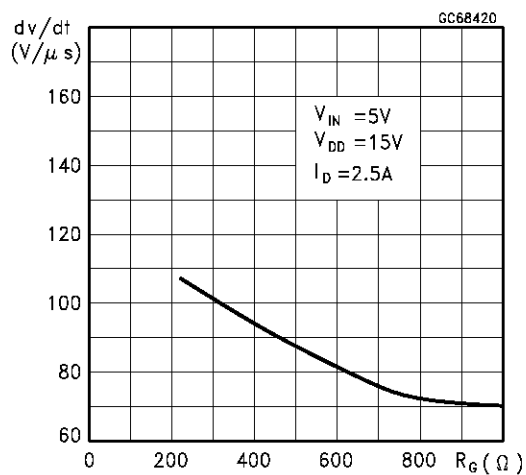
Turn-on Current Slope



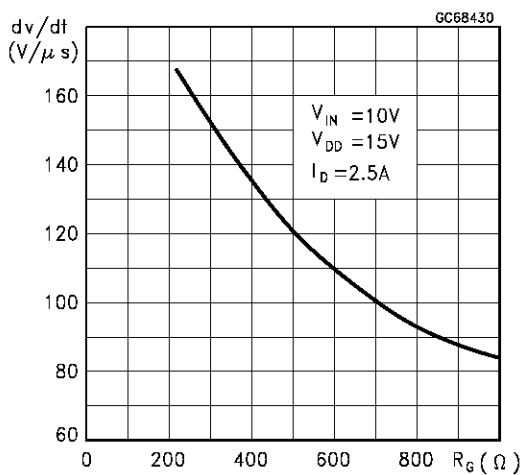
Turn-on Current Slope



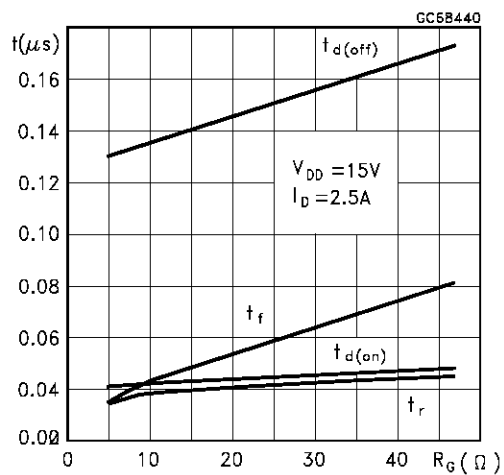
Turn-off Drain-Source Voltage Slope



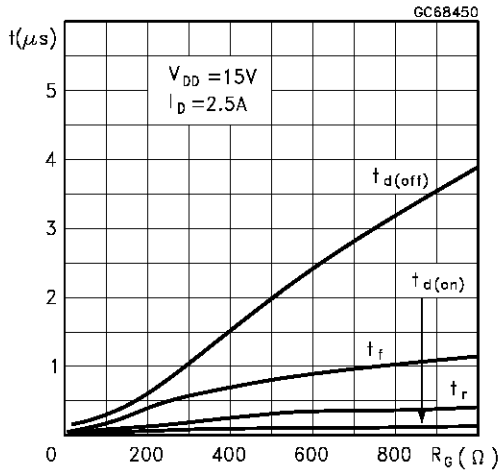
Turn-off Drain-Source Voltage Slope



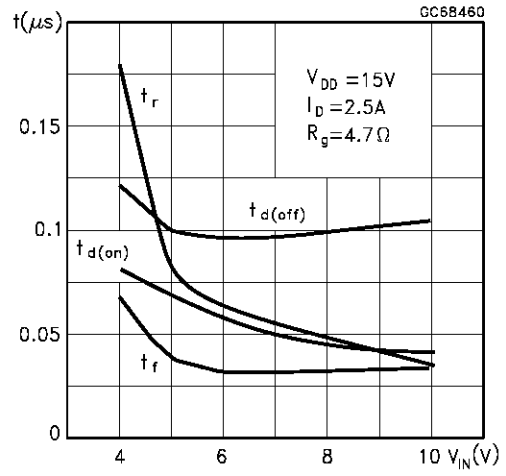
Switching Time Resistive Load



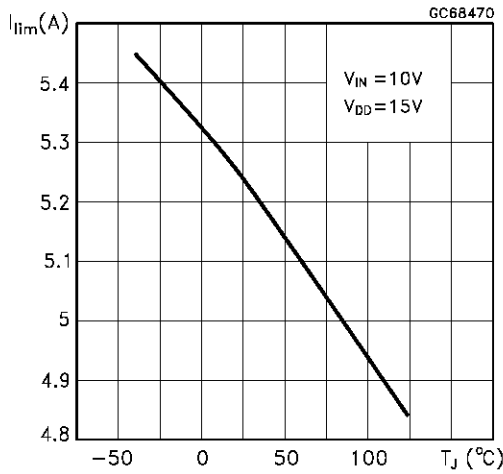
Switching Time Resistive Load



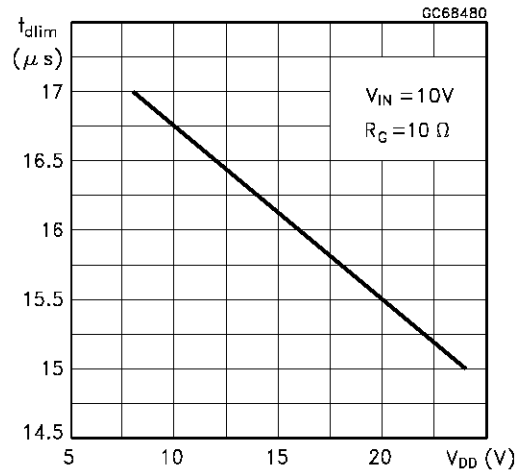
Switching Time Resistive Load



Current Limit vs Junction Temperature



Step Response Current Limit



Source Drain Diode Forward Characteristics

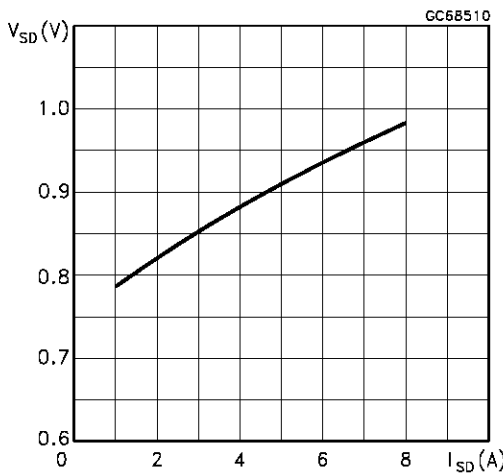


Fig. 1: Unclamped Inductive Load Test Circuits

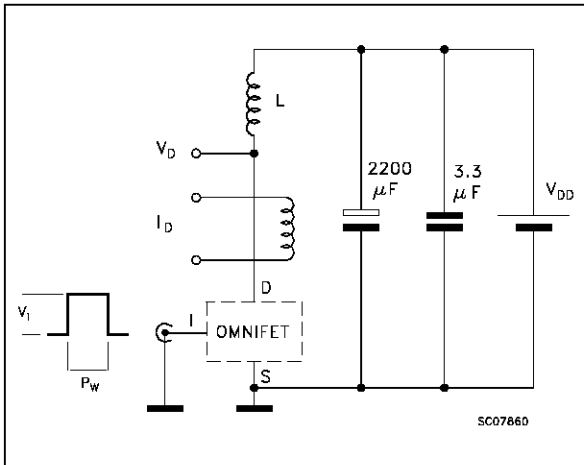


Fig. 2: Unclamped Inductive Waveforms

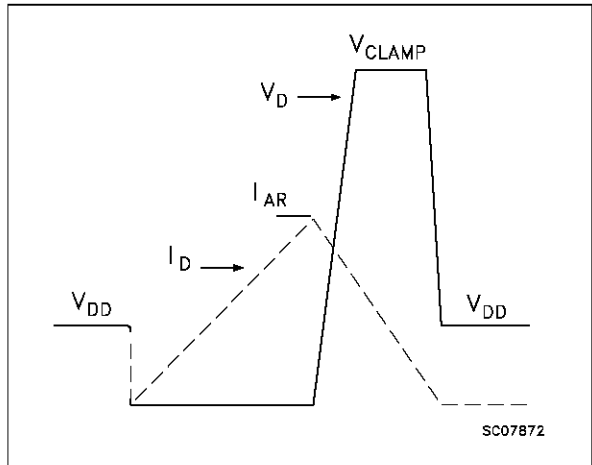


Fig. 3: Switching Times Test Circuits For Resistive Load

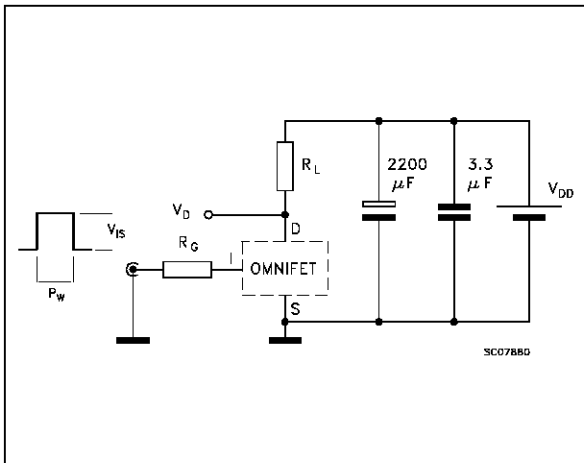


Fig. 4: Input Charge Test Circuit

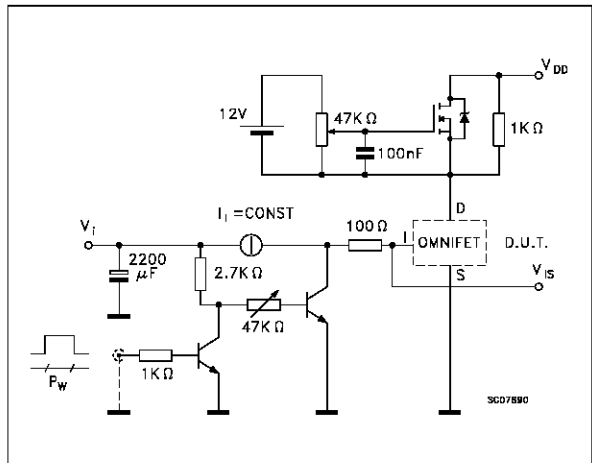


Fig. 5: Test Circuit For Inductive Load Switching And Diode Recovery Times

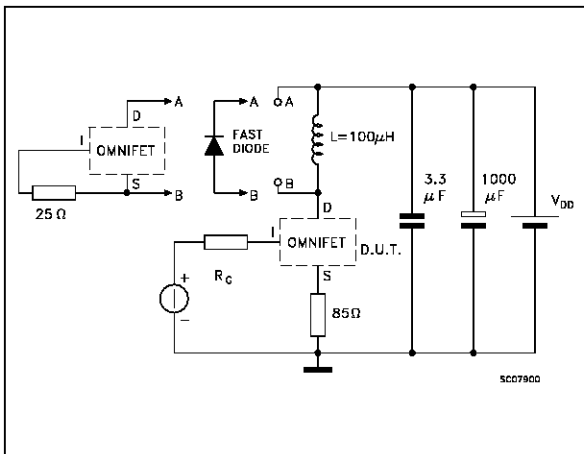
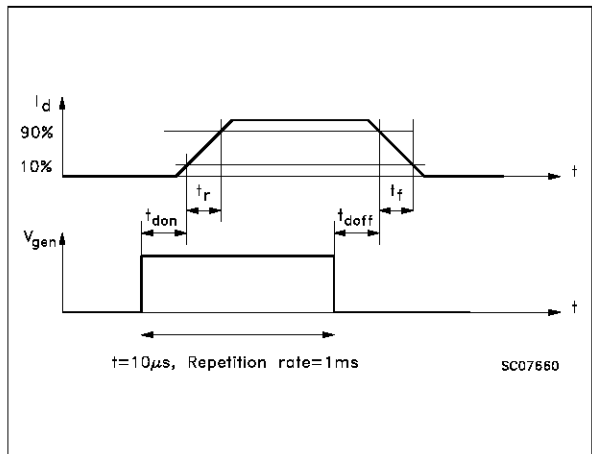
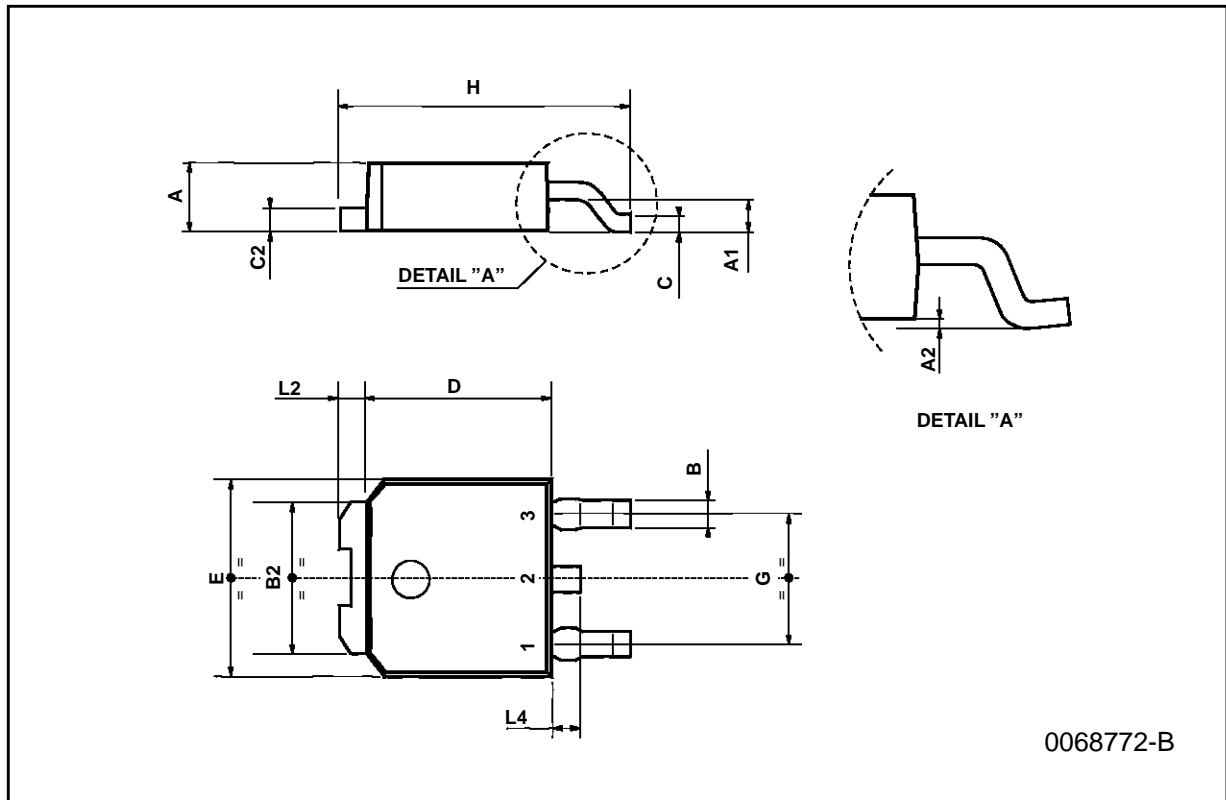


Fig. 6: Waveforms



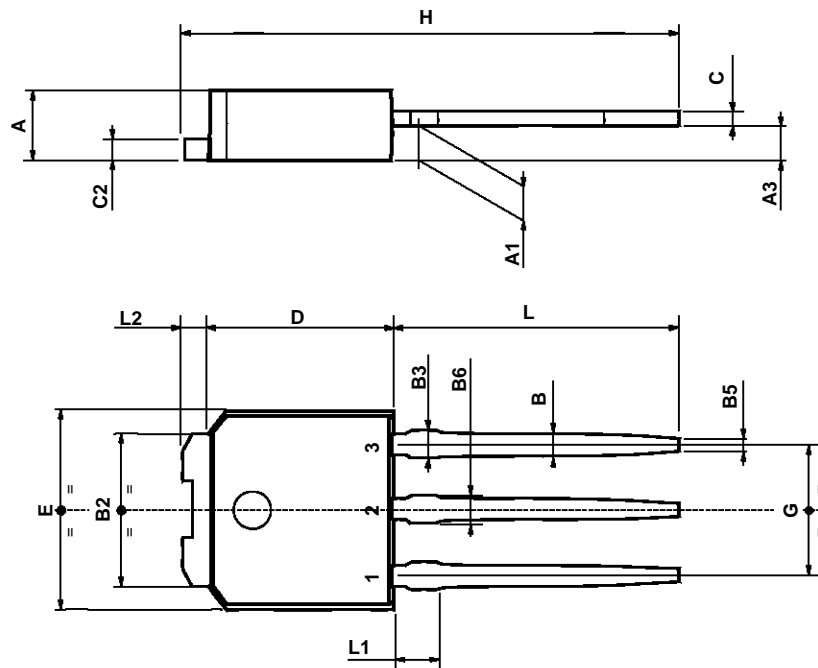
TO-252 (DPAK) MECHANICAL DATA

DIM.	mm			inch		
	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.
A	2.2		2.4	0.086		0.094
A1	0.9		1.1	0.035		0.043
A2	0.03		0.23	0.001		0.009
B	0.64		0.9	0.025		0.035
B2	5.2		5.4	0.204		0.212
C	0.45		0.6	0.017		0.023
C2	0.48		0.6	0.019		0.023
D	6		6.2	0.236		0.244
E	6.4		6.6	0.252		0.260
G	4.4		4.6	0.173		0.181
H	9.35		10.1	0.368		0.397
L2		0.8			0.031	
L4	0.6		1	0.023		0.039



TO-251 (IPAK) MECHANICAL DATA

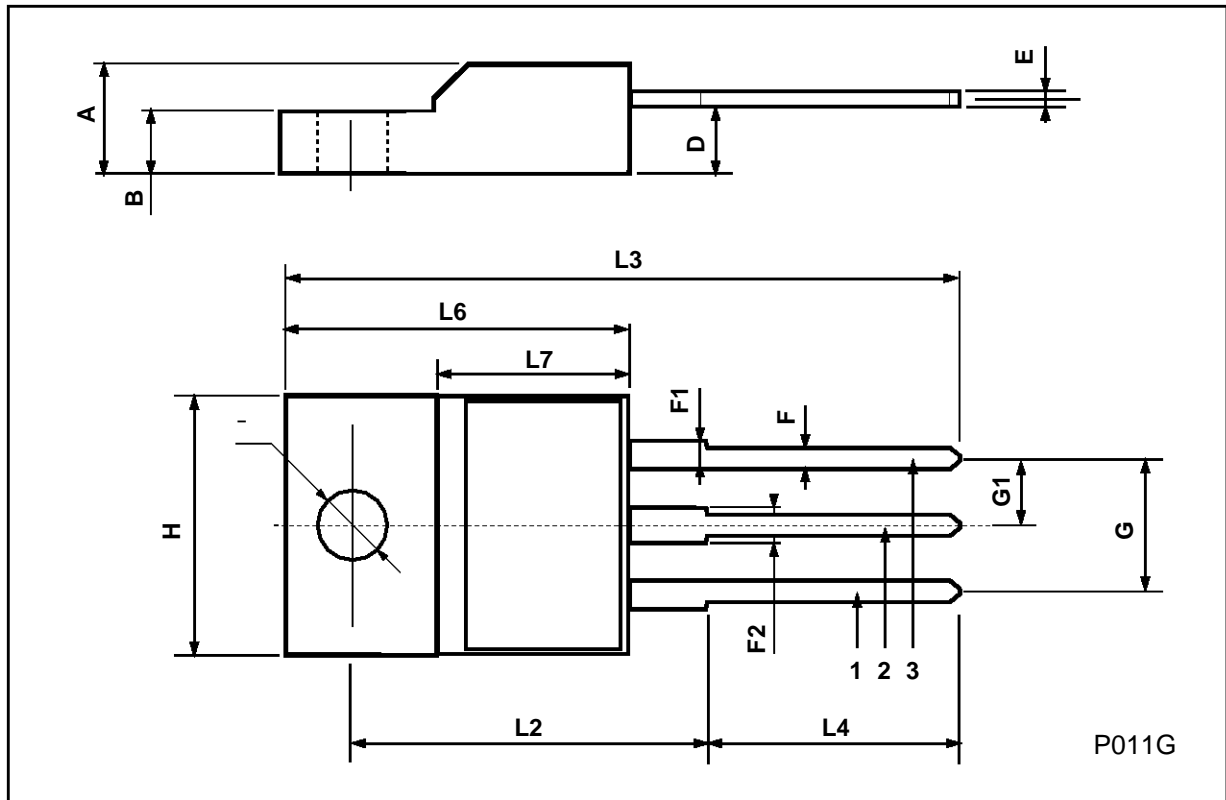
DIM.	mm			inch		
	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.
A	2.2		2.4	0.086		0.094
A1	0.9		1.1	0.035		0.043
A3	0.7		1.3	0.027		0.051
B	0.64		0.9	0.025		0.031
B2	5.2		5.4	0.204		0.212
B3			0.85			0.033
B5		0.3			0.012	
B6			0.95			0.037
C	0.45		0.6	0.017		0.023
C2	0.48		0.6	0.019		0.023
D	6		6.2	0.236		0.244
E	6.4		6.6	0.252		0.260
G	4.4		4.6	0.173		0.181
H	15.9		16.3	0.626		0.641
L	9		9.4	0.354		0.370
L1	0.8		1.2	0.031		0.047
L2		0.8	1		0.031	0.039



0068771-E

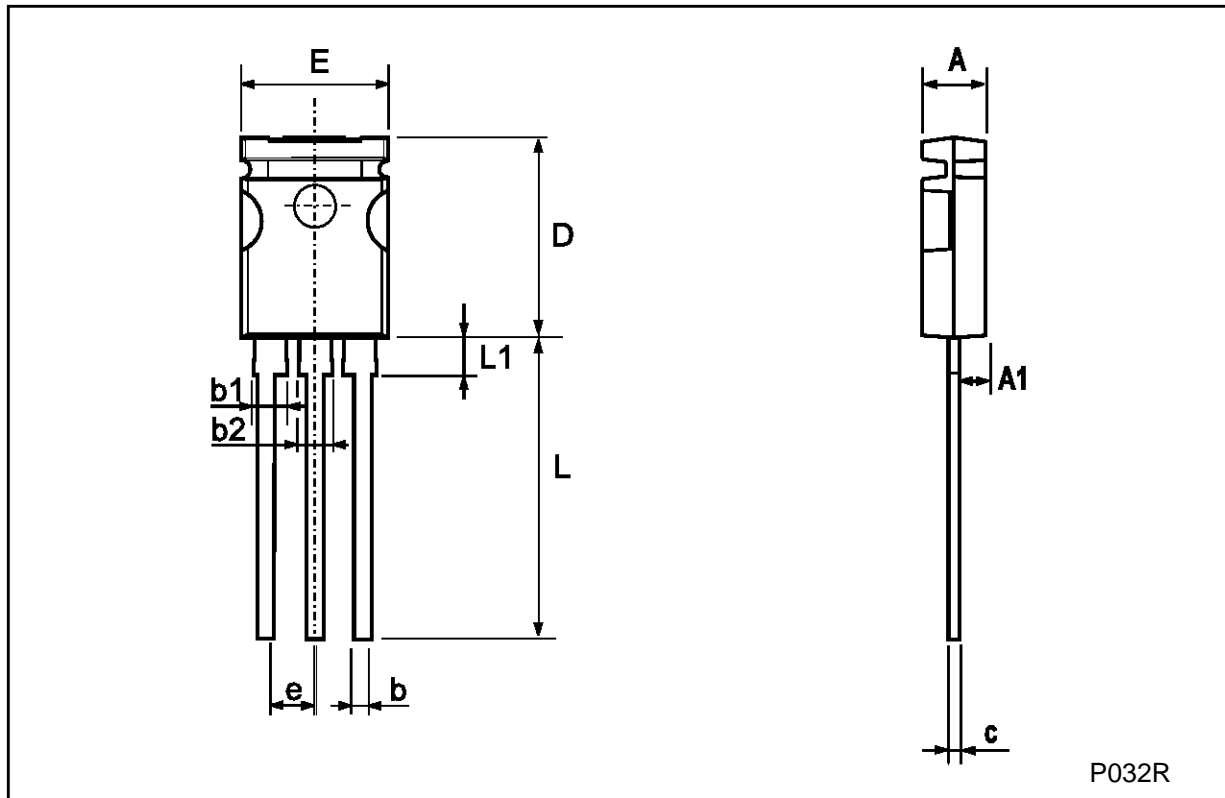
ISOWATT220 MECHANICAL DATA

DIM.	mm			inch		
	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.
A	4.4		4.6	0.173		0.181
B	2.5		2.7	0.098		0.106
D	2.5		2.75	0.098		0.108
E	0.4		0.7	0.015		0.027
F	0.75		1	0.030		0.039
F1	1.15		1.7	0.045		0.067
F2	1.15		1.7	0.045		0.067
G	4.95		5.2	0.195		0.204
G1	2.4		2.7	0.094		0.106
H	10		10.4	0.393		0.409
L2		16			0.630	
L3	28.6		30.6	1.126		1.204
L4	9.8		10.6	0.385		0.417
L6	15.9		16.4	0.626		0.645
L7	9		9.3	0.354		0.366
Ø	3		3.2	0.118		0.126



SOT82-FM MECHANICAL DATA

DIM.	mm			inch		
	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.
A	2.85		3.05	1.122		1.200
A1	1.47		1.67	0.578		0.657
b	0.40		0.60	0.157		0.236
b1	1.4		1.6	0.551		0.630
b2	1.3		1.5	0.511		0.590
c	0.45		0.6	0.177		0.236
D	10.5		10.9	4.133		4.291
e	2.2		2.8	0.866		1.102
E	7.45		7.75	2.933		3.051
L	15.5		15.9	6.102		6.260
L1	1.95		2.35	0.767		0.925



Information furnished is believed to be accurate and reliable. However, SGS-THOMSON Microelectronics assumes no responsibility for the consequences of use of such information nor for any infringement of patents or other rights of third parties which may result from its use. No license is granted by implication or otherwise under any patent or patent rights of SGS-THOMSON Microelectronics. Specifications mentioned in this publication are subject to change without notice. This publication supersedes and replaces all information previously supplied. SGS-THOMSON Microelectronics products are not authorized for use as critical components in life support devices or systems without express written approval of SGS-THOMSON Microelectronics.

© 1996 SGS-THOMSON Microelectronics - Printed in Italy - All Rights Reserved

SGS-THOMSON Microelectronics GROUP OF COMPANIES

Australia - Brazil - Canada - China - France - Germany - Hong Kong - Italy - Japan - Korea - Malaysia - Malta - Morocco - The Netherlands - Singapore - Spain - Sweden - Switzerland - Taiwan - Thailand - United Kingdom - U.S.A

This datasheet has been download from:

www.datasheetcatalog.com

Datasheets for electronics components.